

REMARKS


Claims 55-68 are pending in the application with claims 69-78 cancelled herein without prejudice. Applicant hereby elects Invention I, claims 55-61, with traverse solely for the purpose of responding to the restriction and without admitting to the propriety of the restriction. Applicant traverses on the grounds that each of alleged Inventions I-III are disclosed in the present specification "as capable of use together" with the other Inventions, contrary to the allegation on page 2 of the Office Action. At least page 9, line 5 to page 10, line 17 and page 12, line 13 to page 13, line 14 support Applicant's assertion. Accordingly, the Office's basis for restriction is improper. Also, claims 69-78 are cancelled herein, reducing the number of alleged inventions.

The referenced portions of the specification state that one advantage of a conductive connection forming method and an integrated circuit via forming method, such as set forth in respective claims 55 and 64, is that they protect from oxidation, as set forth in claim 62. Similarly, the specific oxidation protection method of claim 62 may be used as a part of a conductive connection forming method or an integrated circuit via forming method, such as set forth in respective claims 55 and 64. Further, an integrated circuit wire bond forming method, such as set forth in claim 64, is but one type of a conductive connection forming method, as set forth in claim 55. At least for such reasons, Applicants request consideration of claims 55-68 in the next Action.

Respectfully submitted,

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